



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Mc CORMACK, MARK JEE PROCESS.  
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Serial No.: 09/834,273 2001 JUL 12 P 3: 00

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For: METHOD AND STRUCTURE OF  
DEPOSITING SOLDER BUMPS  
ON A WAFER (99-32)

Group Art Unit: 2812

Attorney Docket No: P53945US0

US PATENT &  
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JUL 24 2001  
TC 1700

2812  
#4  
10/29/01  
Mollen

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Commissioner for Patents  
Washington, D.C. 20231

Sir:

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